

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DT01 Rec'd PCT/PTC 30 DEC 2004

Applicants: H. MATSUURA, et al.

Application No.: TBD

Filed: December 30, 2004

For: ADHESIVE FILM FOR SEMICONDUCTOR USE, METAL
SHEET LAMINATED WITH ADHESIVE FILM, WIRING
CIRCUIT LAMINATED WITH ADHESIVE FILM, AND
SEMICONDUCTOR DEVICE USING SAME, AND METHOD
FOR PRODUCING SEMICONDUCTOR DEVICE

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

December 30, 2004

Sir:

Please amend the above-identified application, prior to calculation of the filing
fee, as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the amendments.